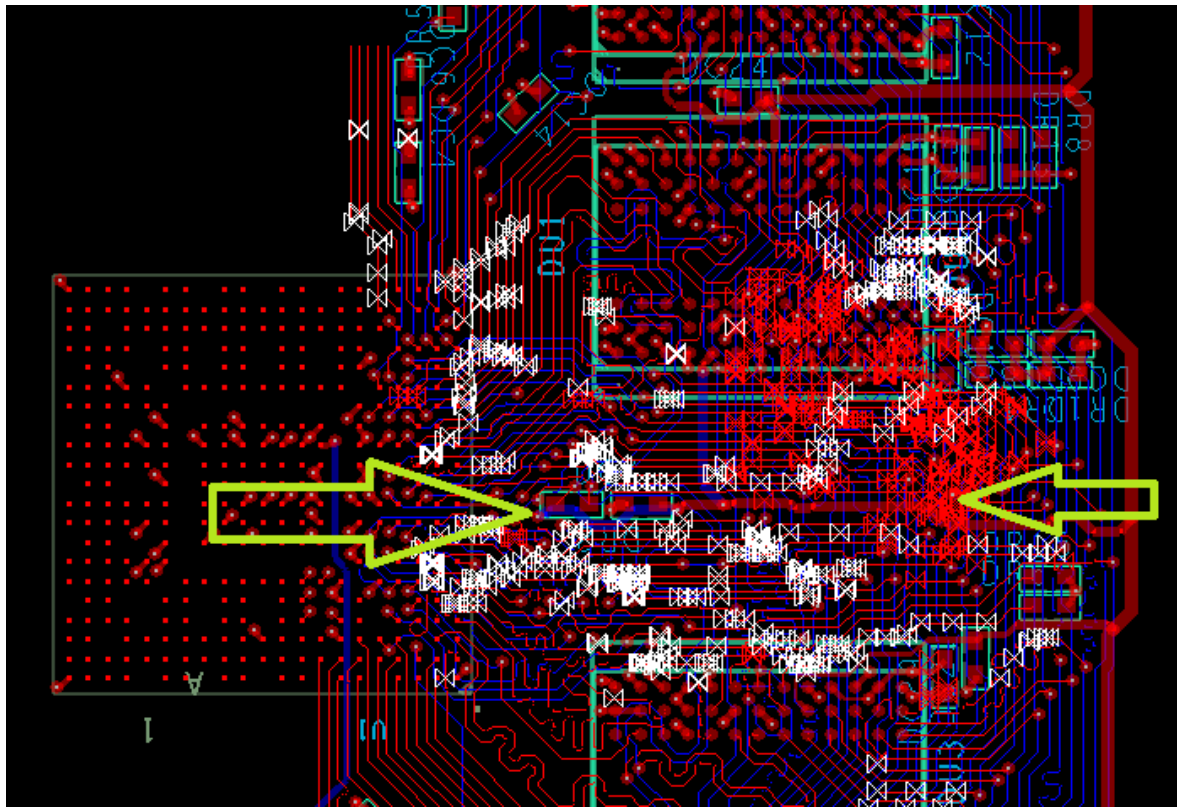


|   |   |                   |                 |               |                 |                        |                 |                   |              |
|---|---|-------------------|-----------------|---------------|-----------------|------------------------|-----------------|-------------------|--------------|
| 1 | Stackup - Impadence -Trace Width                        |                   |                 |               |                 |                        |                 |                   |              |
|   | Total layers: 4   |                   |                 |               |                 |                        |                 |                   |              |
|   | Board thickness: 1.6 mm +/- 10%                         |                   |                 |               |                 |                        |                 |                   |              |
|   | PCB material: Typical FR4                               |                   |                 |               |                 |                        |                 |                   |              |
|   | Surface finish: ENIG(化学镀金)                              |                   |                 |               |                 |                        |                 |                   |              |
|   | Stackup Control Table                                   |                   |                 |               |                 |                        |                 |                   |              |
|   | --  | Stackup Structure |                 |               |                 | Impedance Requirements |                 |                   |              |
|   | Layer   | Type              | Thickness (mil) |               | Dk(with Sim Z0) | Impedance spec (Ohms)  | Reference layer | Width/space (mil) | Sim Z0(Ohms) |
|   |   | solder mask       | 0.5             | SM            | 4.25            |                        |                 |                   |              |
|   | 1   | TOP               | 1.6             | 0.3oz+plating |                 | 50±10%                 | 2               | 4                 | 52.18        |
|   |   |                   |                 |               |                 | 90±10%                 | 2               | 4.5/7.5           | 90.03        |
|   |   |                   |                 |               |                 | 100±10%                | 2               | 3.8/8.7           | 98.5         |
|   |   | prepreg           | 2.9             |               | 4               |                        |                 |                   |              |
|   | 2   | GND               | 1.2             | 1.0oz         |                 |                        |                 |                   |              |
|   | core  | 50.0              |                 | 4.5           |                 |                        |                 |                   |              |
| 3 | VCC   | 1.2               | 1.0oz           |               |                 |                        |                 |                   |              |
|   | prepreg   | 2.9               |                 | 4             |                 |                        |                 |                   |              |
| 4 | BOTTOM  | 1.6               | 0.3oz+plating   |               | 50±10%          | 3                      | 4               | 52.18             |              |
|   |   |                   |                 |               | 90±10%          | 3                      | 4.5/7.5         | 90.03             |              |
|   |   |                   |                 |               | 100±10%         | 3                      | 3.8/8.7         | 98.5              |              |
|   | solder mask   | 0.5               | SM              | 4.25          |                 |                        |                 |                   |              |
|   | Board thickness:  | 62.4              |                 |               |                 |                        |                 |                   |              |
| 2 | 走线宽度  |                   |                 |               |                 |                        |                 |                   |              |
|   | 单端：4mil。  |                   |                 |               |                 |                        |                 |                   |              |
|   | 差分：3.8/8.7mil。  |                   |                 |               |                 |                        |                 |                   |              |
|   | 电源和地Fanout线宽：≥8mil。                                     |                   |                 |               |                 |                        |                 |                   |              |
| 3 | 间距  |                   |                 |               |                 |                        |                 |                   |              |
|   | 单端：数据线与线的间距（Air Gap）≥8mil                               |                   |                 |               |                 |                        |                 |                   |              |
|   | 地址控制线的间距大部分（Air Gap）≥8mil, 小部分间距>=6mil, 此部分主要集中于T点处，见下图 |                   |                 |               |                 |                        |                 |                   |              |



差分线：到其他网络走线间距 $\geq 12\text{mil}$ 。

电源与地：到其他网络走线的间距 $\geq 15\text{mil}$ 。

VREF：到其他网络走线的间距 $\geq 15\text{mil}$ 。

BGA区域里：线与线 $4\text{mil}$ ；线与SMD PIN  $4\text{mil}$ ；线与过孔 $4\text{mil}$ 。

#### 4 拓扑

DQ：点对点

DQS、DQSB：点对点

对于时钟：

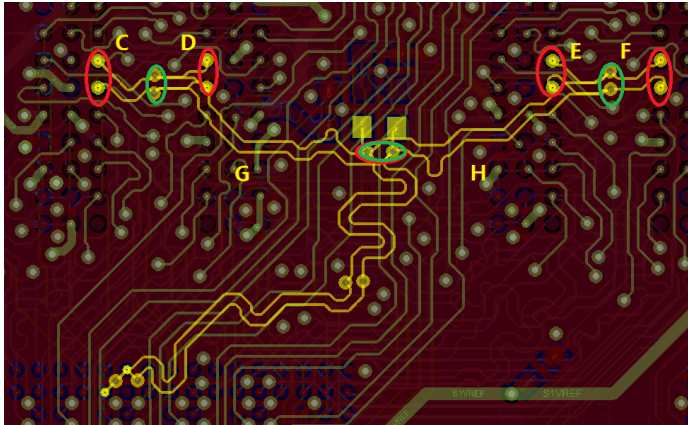
C, D, E, F  $< 500\text{mil}$ ,

C - D  $< +/- 50\text{mil}$ ,

E - F  $< +/- 50\text{mil}$ ,

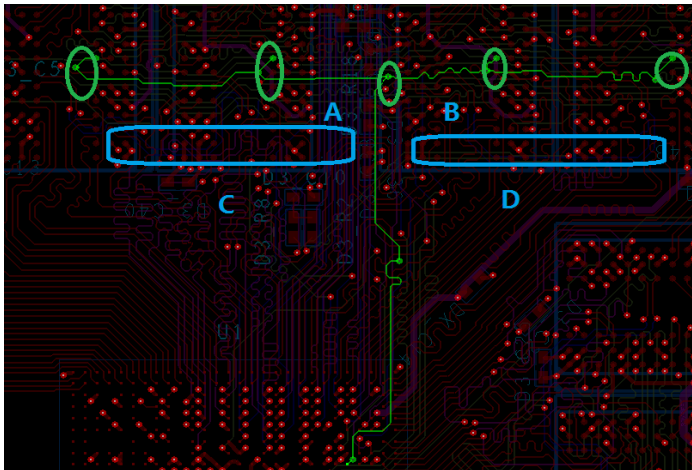
G, H  $< 800\text{mil}$ ,

G - H  $< +/- 50\text{mil}$ 。



对于地址控制:

$|A-B| \leq 50\text{mil}$ ,  $|C-D| \leq 50\text{mil}$ 。



## 5 等长

DQ0-7: 相对于DQS0、DQSB0做等长, 误差范围为 $\leq 90\text{mil}$ 。  
DQ8-15: 相对于DQS1、DQSB1做等长, 误差范围为 $\leq 90\text{mil}$ 。  
DQ16-23: 相对于DQS2、DQSB2做等长, 误差范围为 $\leq 90\text{mil}$ 。  
DQ24-31: 相对于DQS3、DQSB3做等长, 误差范围为 $\leq 90\text{mil}$ 。

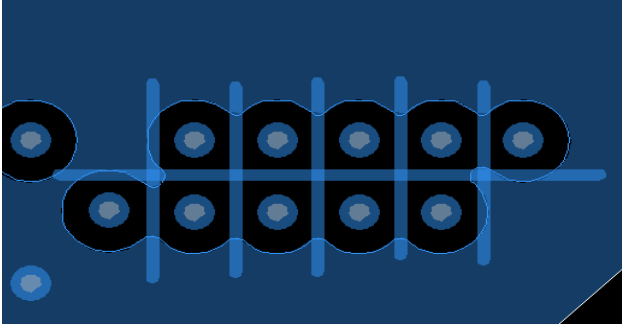
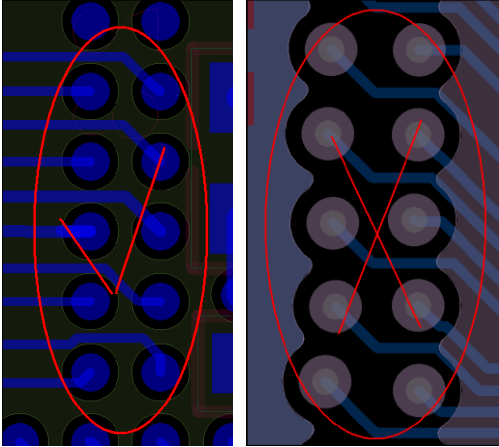
DQSx、DQSBx:  
相对于CK/CKB信号做等长, 误差范围为 $\leq 900\text{mil}$ 。

Ax、BAx、CAS、RAS、WE、CSx、ODTx、CKEx:  
相对于CK/CKB信号做等长, 误差范围为 $\leq 800\text{mil}$ 。

DQSx与DQSBx等长, 等长误差范围为 $\leq 10\text{mil}$ 。  
CK与CKB等长, 等长误差范围为 $\leq 10\text{mil}$ 。

信号线做等长时要考虑过孔长度的影响

## 6 电源、地平面

|   |   |
|---|---|
|   | <p>平面比较完整，调整好过孔的位置、间距，减少对电源、地平面的破坏。平面断开处用走线连接</p>  |
|   | <p>电源、地平面同时也是信号的参考层要求，不能有信号线的参考层被割断的现象</p>        |
| 7 | <p><b>滤波电容：</b></p>   |
|   | <p>对于单面布局：尽量靠近电源PIN放置，每个电容至少各一个电源过孔和地过孔。</p>  |

## 1. Declaration

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